



Product Change Notification / LIAL-15QPNY176

Date:

19-Jan-2021

Product Category:

Instrumentation Amplifier, Linear Op Amps, Memory, Temperature Sensors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4506 Initial Notice: Qualification of MMT as an additional assembly site for selected products available in 8L TDFN (2x3x0.8mm) package.

Affected CPNs:

[LIAL-15QPNY176_Affected_CPN_01192021.pdf](#)

[LIAL-15QPNY176_Affected_CPN_01192021.csv](#)

Notification Text:

PCN Status:Initial notification.

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MMT as an additional assembly site for selected products available in 8L TDFN (2x3x0.8mm) package.

Pre Change:

Assembled at NSEB using gold (Au) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire and 8200T die attach or 8600 die attach material.

Post Change:

Assembled at NSEB using gold (Au) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire and 8200T die attach or 8600 die attach material or assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire and 3280 die attach material.

Pre and Post Change Summary:

	Pre Change		Post Change		
Assembly Site	UTAC Thai Limited (UTL-1) LTD. NSEB		UTAC Thai Limited (UTL-1) LTD. NSEB	Microchip Technology Thailand (Branch)/ MMT	
Wire material	Au	CuPdAu	Au	CuPdAu	CuPdAu
Die attach material	8200T	8600	8200T	8600	3280
Molding compound material	G700LTD		G700LTD		G700LTD
Lead frame material	A194		A194		A194
Lead Frame Lead Lock	No		No		No

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:February 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	December 2020					-->	February 2021				
Workweek	49	50	51	52	53		05	06	07	08	09
Initial PCN Issue Date				X							
Qual Report Availability										X	
Final PCN Issue Date										X	

Method to Identify Change: Traceability code

Qualification Plan Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:**December 21, 2020:** Issued initial notification.**January 19, 2021:** Re-issued initial notification to update the pre and post change summary to correct the lead frame lead lock of NSEB from Yes to No.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-15QPNY176_Pre and Post Change Lead frame comparison Rev 1.pdf
PCN LIAL-15QPNY176_Qual Plan.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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